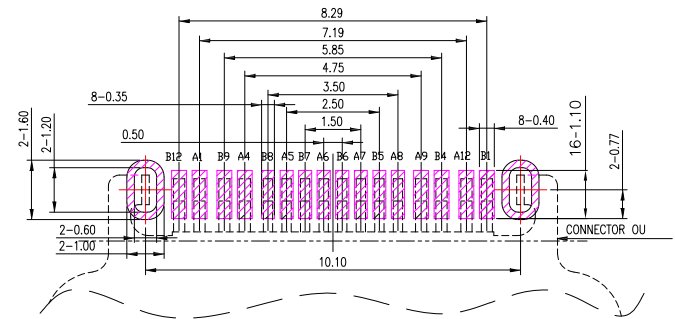


IPX7



SBC-WP160M3-20x-S165

鍍層厚度：
Blank : 1u"
2 : 15u"
3 : 30u"



RECOMMENDED PCB LAYOUT

PIN ASSIGNMENTS

No.	NAME	DESCRIPTION	No.	NAME	DESCRIPTION
A1	GND	GROUND RETURN	B12	GND	SIGNAL PIN, NOT CONTACT GND
A4	VBUS	BUS POWER	B9	VBUS	BUS POWER
A5	CC1	CONFIGURATION CHANNEL	B8	SBU2	SIDEBAND USE(SBU)
A6	DP1	POSITIVE HALF OF USB2.0 DIFFERENTIAL PAIR-POSITION1	B7	DN2	NEGATIVE HALF OF USB2.0 DIFFERENTIAL PAIR-POSITION2
A7	DN1	NEGATIVE HALF OF USB2.0 DIFFERENTIAL PAIR-POSITION1	B6	DP2	POSITIVE HALF OF USB2.0 DIFFERENTIAL PAIR-POSITION2
A8	SBU1	SIDEBAND USE(SBU)	B5	CC2	CONFIGURATION CHANNEL
A9	VBUS	BUS POWER	B4	VBUS	BUS POWER
A12	GND	GROUND RETURN	B1	GND	GROUND RETURN
NO PLATE	GND	GROUND RETURN,CONTACT A1	NO PLATE	GND	GROUND RETURN,CONTACT A12&B1

SPECIFICATIONS

Electrical:

- 1.Rating: 5.0V , 3.0 A
- 2.Contact Resistance: 30 mΩ Max
- 3.Insulation Resistance: 100 MΩ Min

Mechanical:

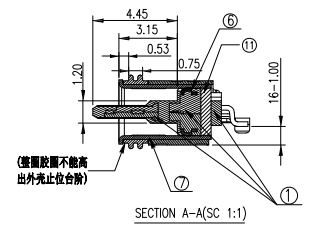
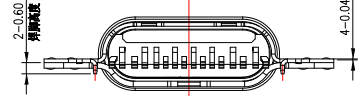
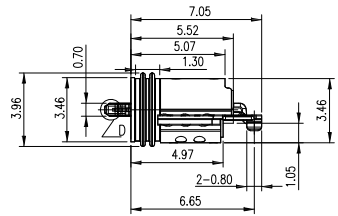
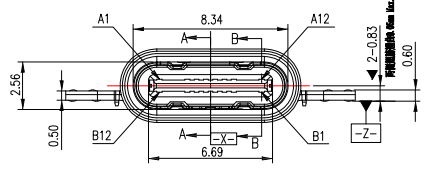
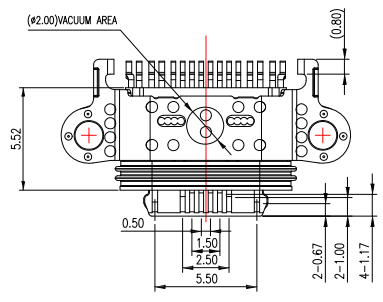
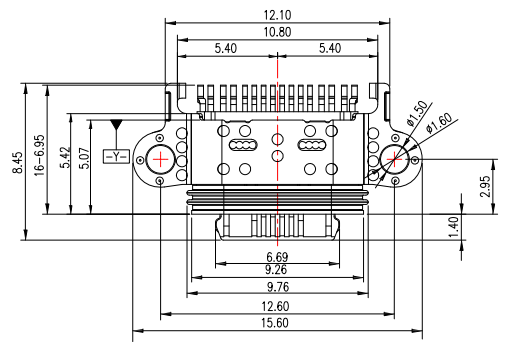
- 1.Connector Mate and Unmate Force
 - 1.1 Mate force: 5~20 N
 - 1.2 Unmate force: 8~20 N

Material:

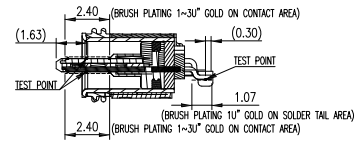
- 1.Housing: PA46
- 2.Contact: C18150 / C7025
- 3.Shell: SUS

Finish:

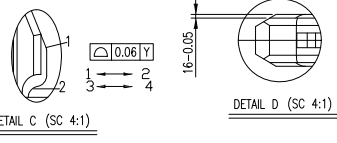
- 1.Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer



SECTION A-A(SC 1:1)

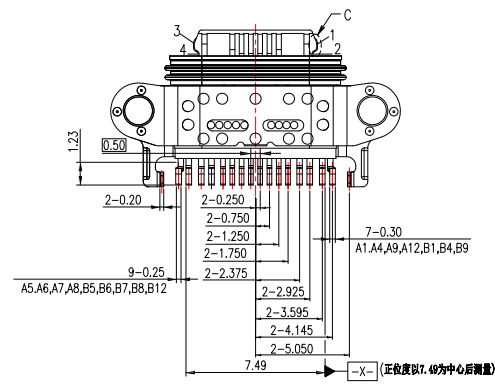


SECTION B-B(SC 1:1)



DETAIL C (SC 4:1)

DETAIL D (SC 4:1)



CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S



UNITS

MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	04/01/22	FINISH	MODLE	USB TYPE C 2.0 沉板 2.41mm 防水型IPX7
CHECKED BY:	DATE	SCALE	DWG NO.	SBC-WP160M3-20x-S165
Jacky Chen	04/01/22	1 : 1	PART NO.	SBC-WP160M3-20x-S165
APPROVED BY:	DATE	SHEET NO.	1 of 1	
Tony Kao	04/01/22			

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	新增PCB LAYOUT尺寸	Jack	040122